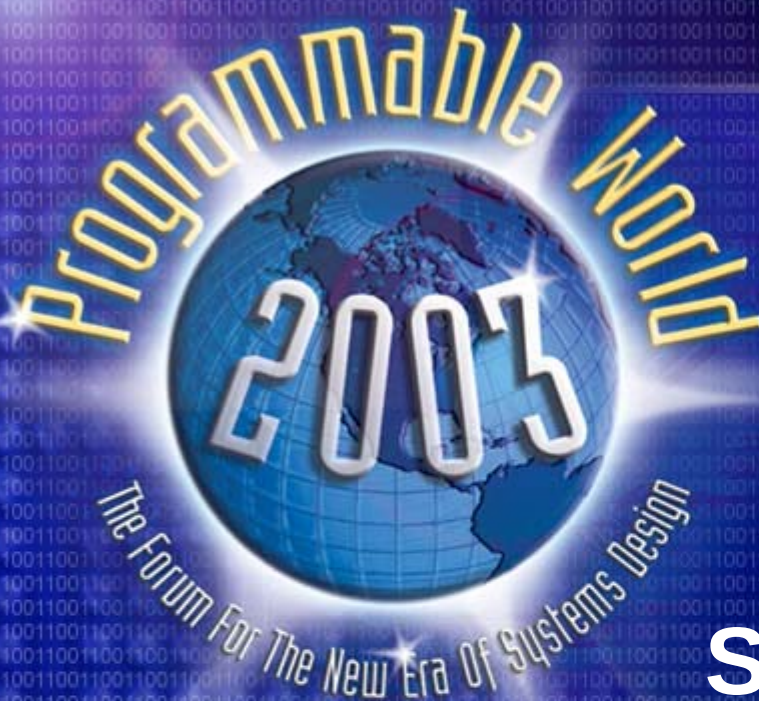
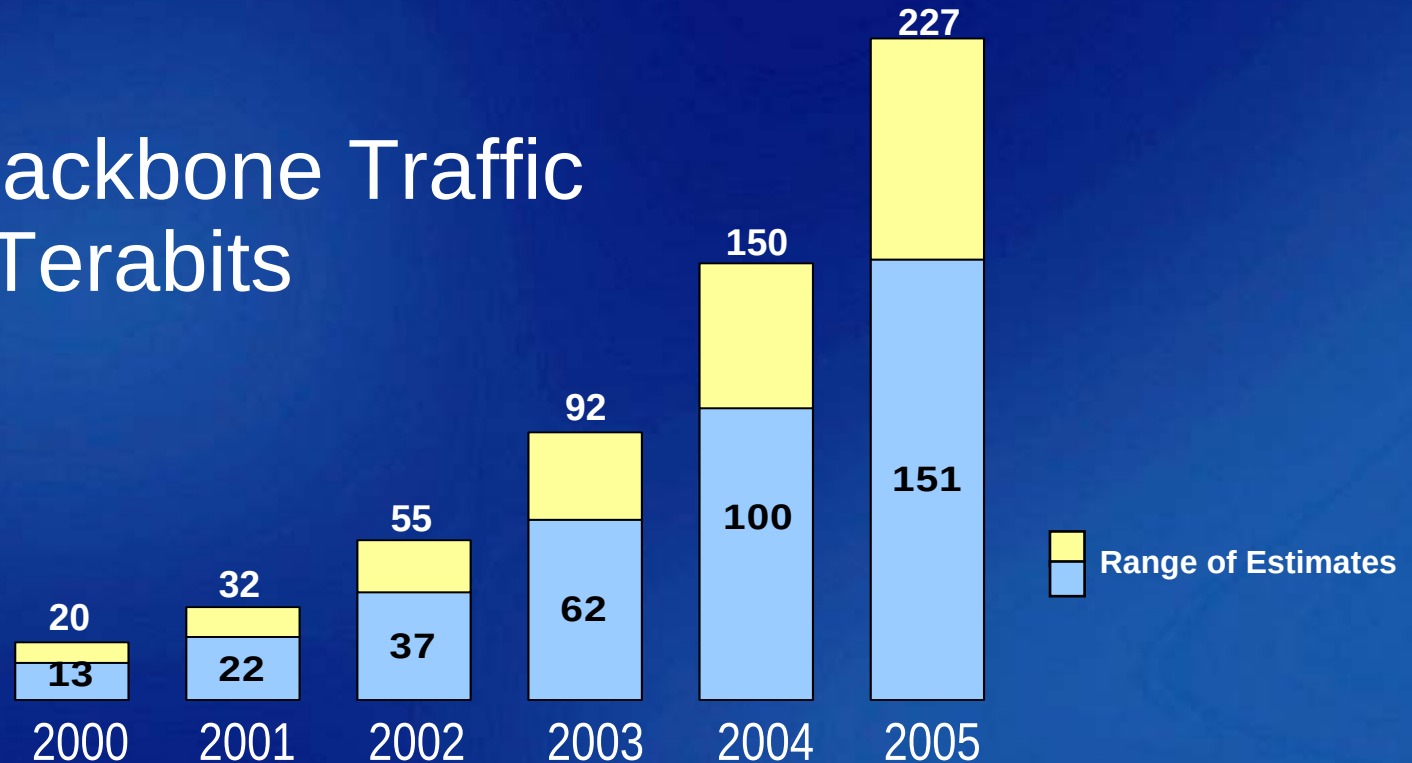




Solving the Connectivity Challenge

Traffic Demand Remains Healthy

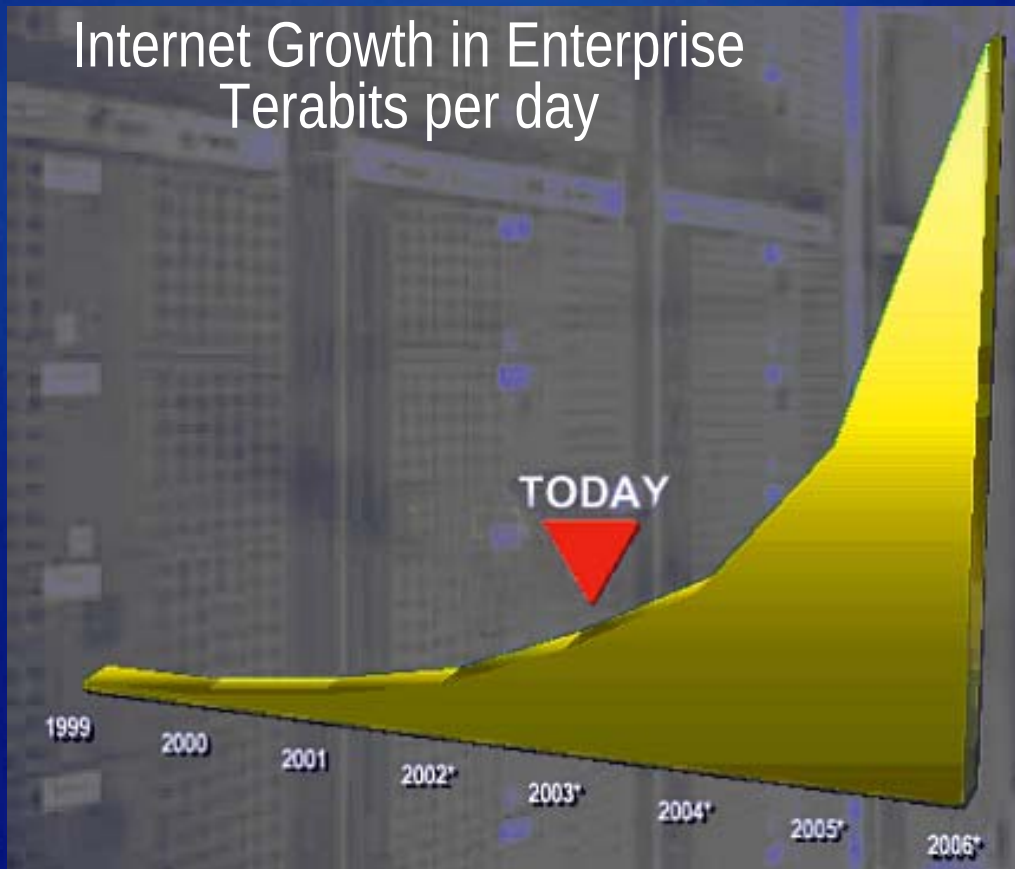
Average Backbone Traffic in Terabits



- Carriers are finding innovative ways to address traffic demand such as reusing and redeploying systems and rerouting traffic
- Challenge for equipment suppliers and IC suppliers is to deliver flexibility

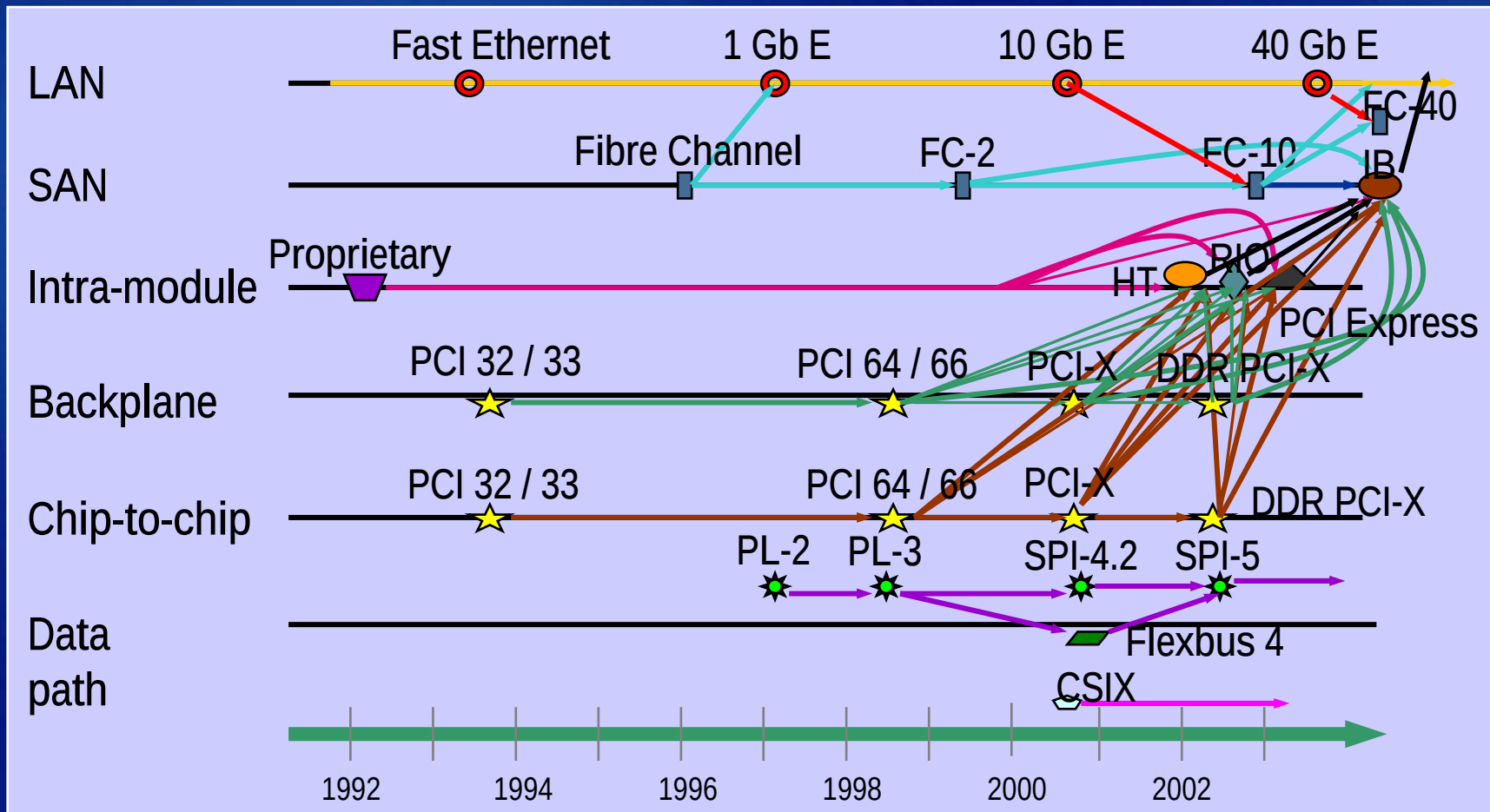
Industry 10 Gbps Deployment

Internet Growth in Enterprise
Terabits per day



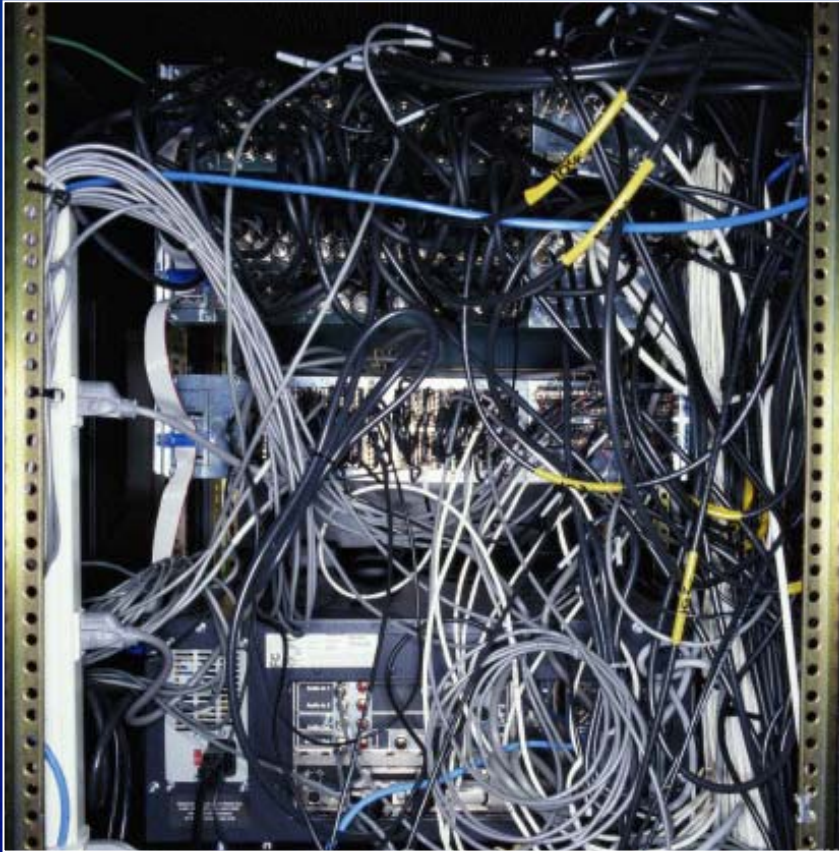
- Driven by insatiable demand for data, voice and video
 - Wireless web, video conferencing, camera cell phones, NetMeeting, IP phone
- A sum of all parts:
 - Cost, power, density, reach
- 10 Gbps systems offer the best performance at the lowest cost per bit!

Explosion of New Connectivity Standards



A typical Terabit System uses 2 or more interfaces at the same time!

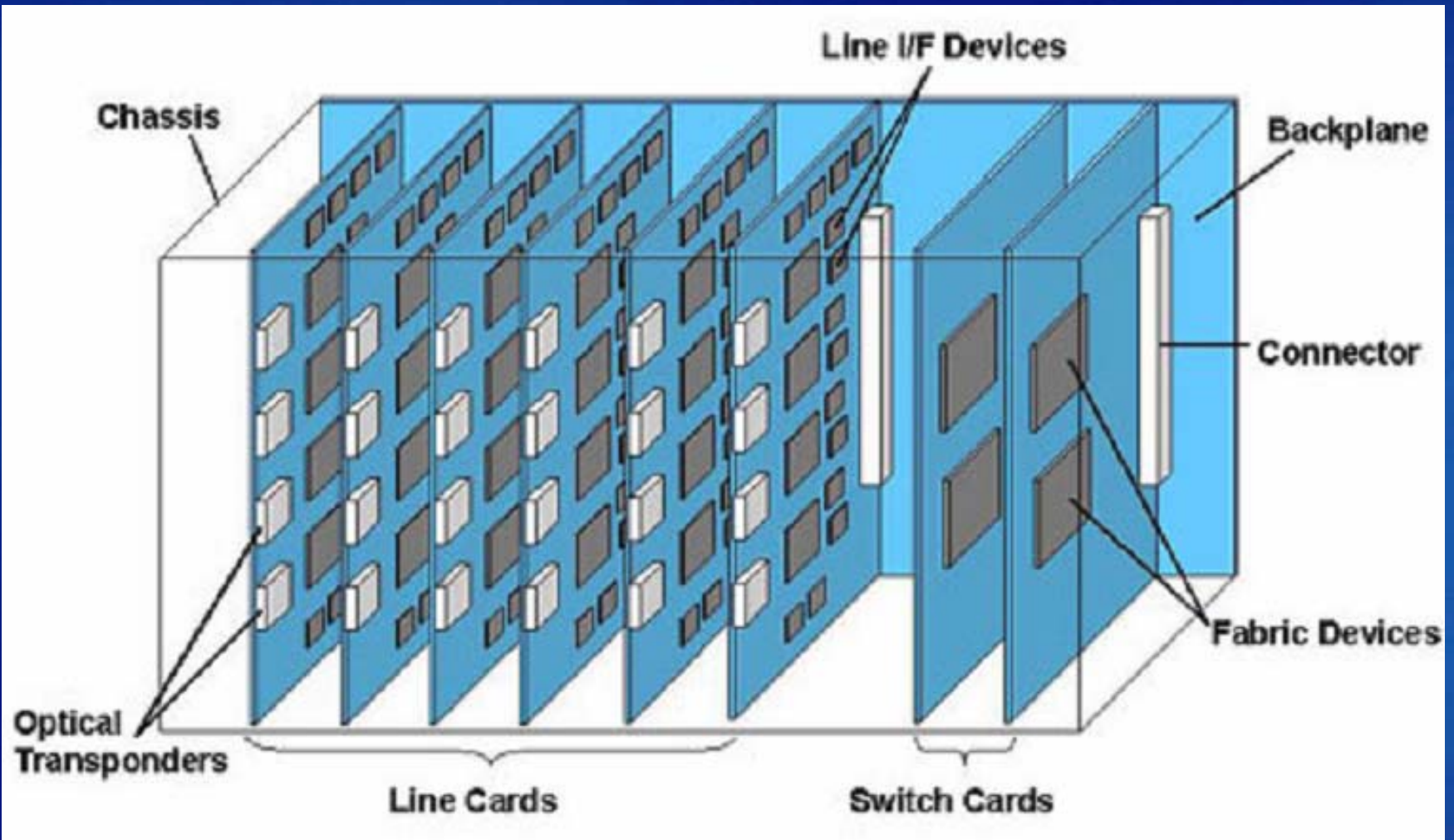
The Edge is a Mess...



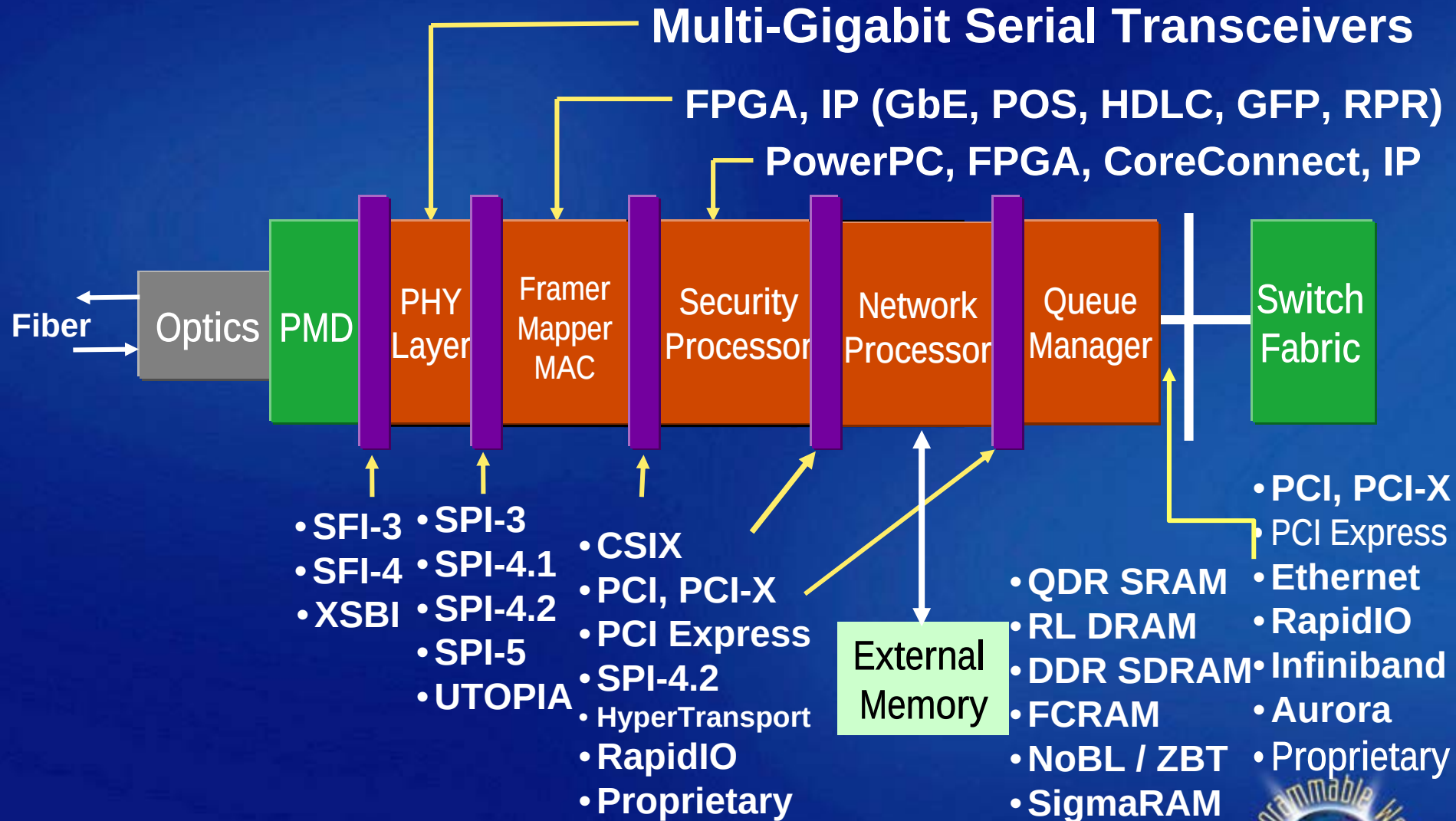
Actual Rack in Carrier POP

- Different physical routers dedicated to different users and services
- Intra-POP connectivity nightmare
- Complex standards and protocols
- Space, power, cooling are at a premium

Typical Networking System

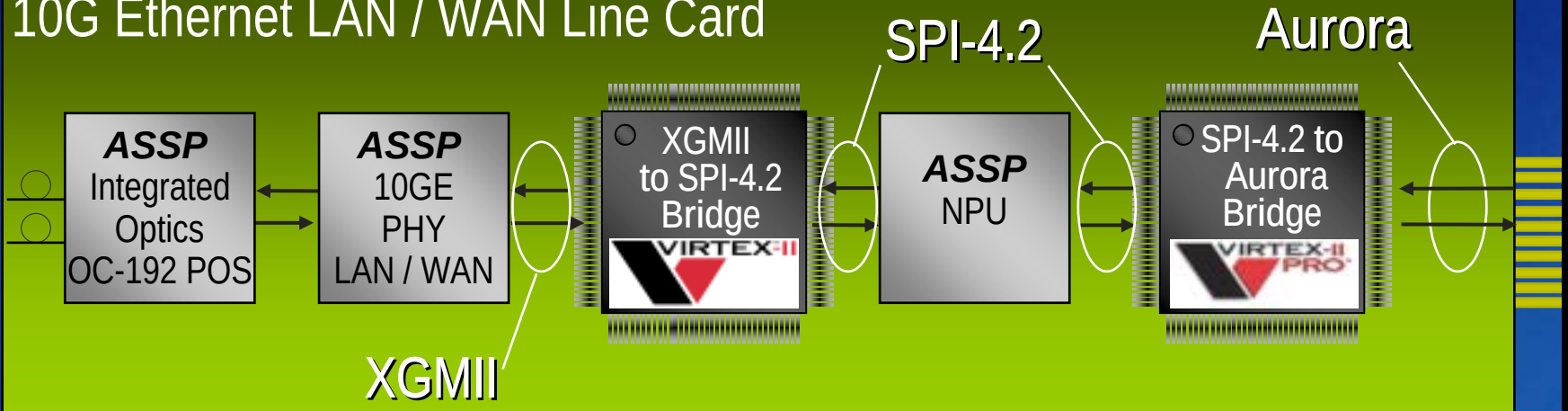


Protocol Interfaces

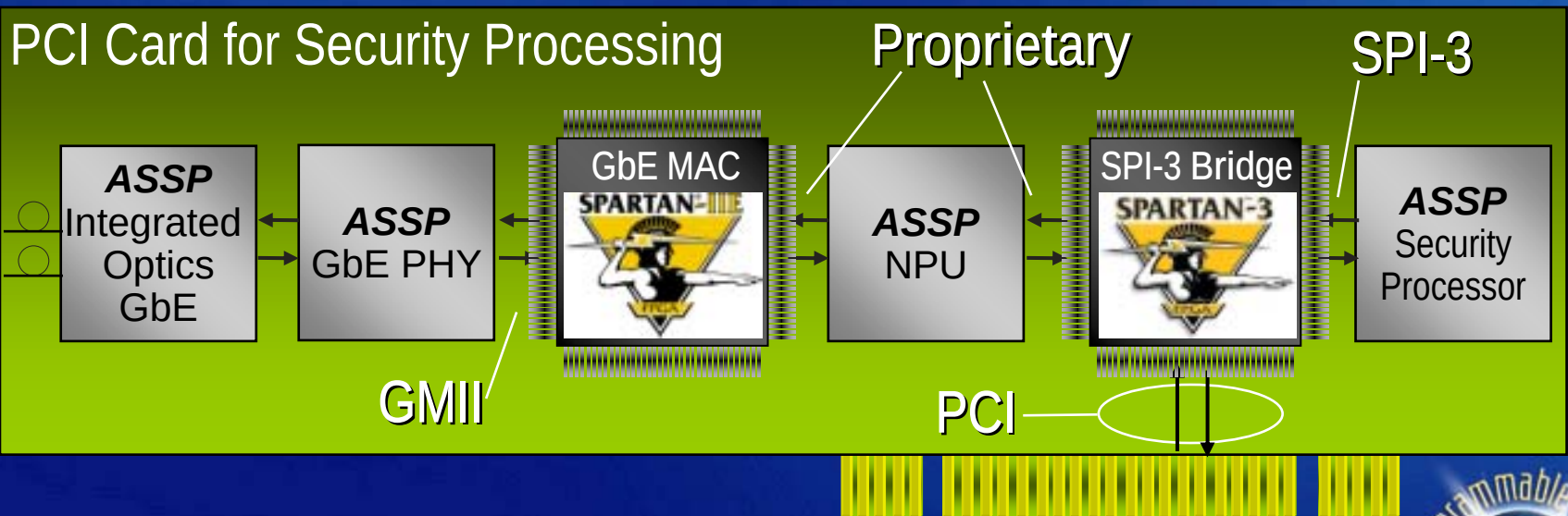


Diverse Component Mix

10G Ethernet LAN / WAN Line Card

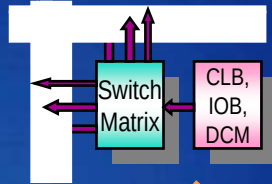


PCI Card for Security Processing

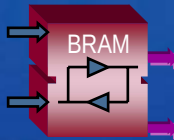


Connectivity Needs Powerful Platform FPGA Features

Active Interconnect™
Fast, predictable routing delays



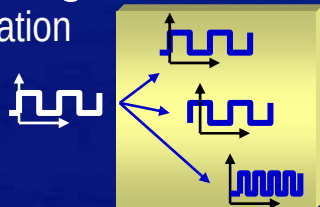
Dual-Port RAM
Fast & efficient logic;
Highest flexibility



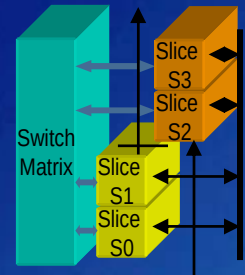
On-chip termination
Reduced lay-out complexity



Digital Clock Managers
Precise frequency generation
and phase control



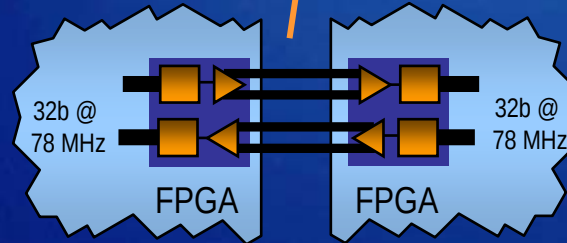
Powerful CLB
>300 MHz Performance



Programmable I/Os
840 Mbps LVDS
644 Mbps SDR

Embedded PowerPC
300 MHz; 420 DMIPS

Multi-Gigabit Serial Transceivers
Up to (24) 3.125 Gbps transceivers



Lowest Cost Parallel Interconnect Solutions

- PCI 32/33 effective cost as low as \$0.75*
- Physical interfaces and system elements
 - 25 I/O standards, DDR I/O registers, DCMs
- Pre-engineered solution
 - Drop-in functionality
 - Pre-verified and fully compliant



PCI 32/33 and PCI 64/33

Real-PCI™

SPI-3 (POS-PHY Level 3)

SPI-4.2 "Lite" (2.5Gbps)

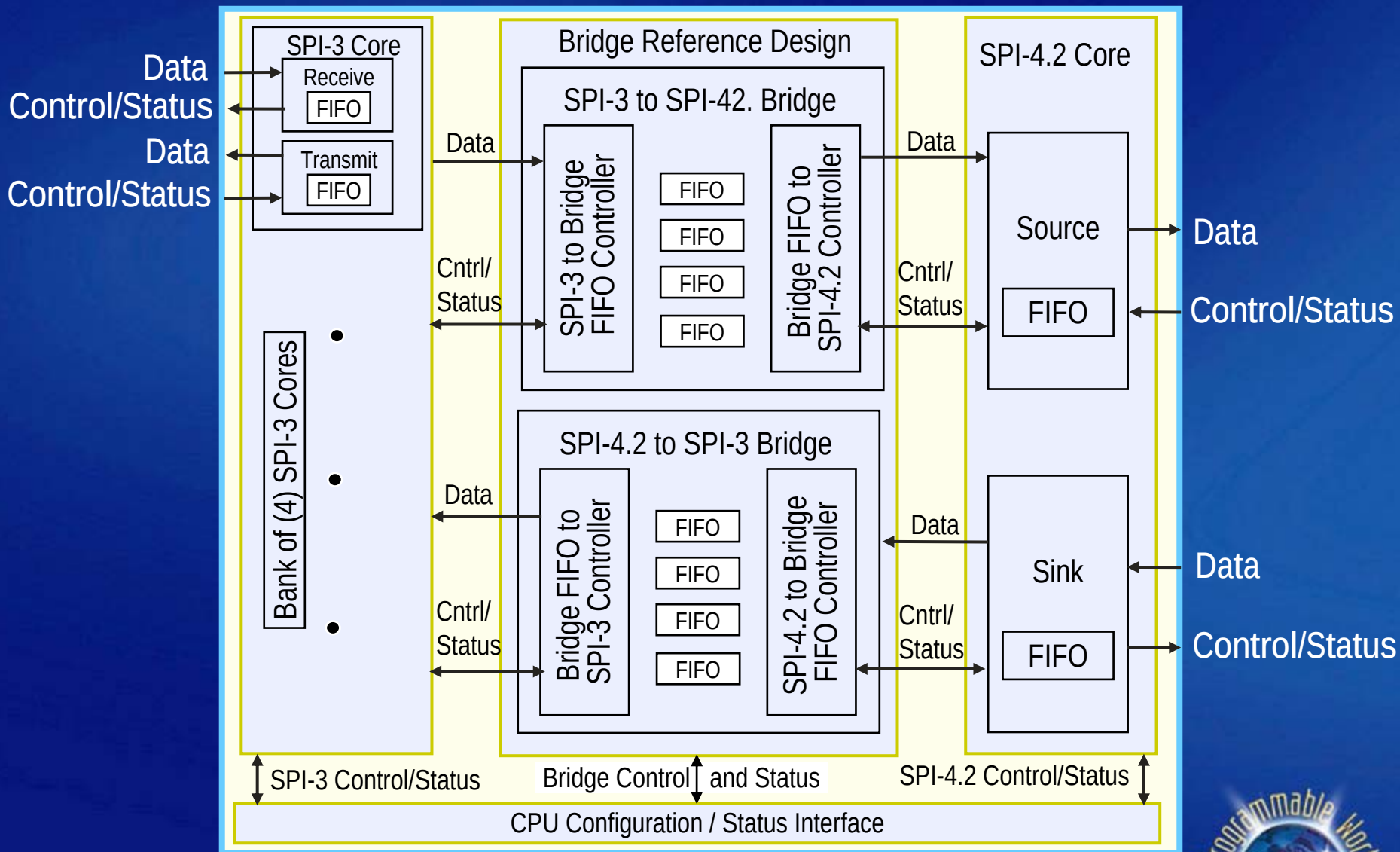


Bridging Case Studies

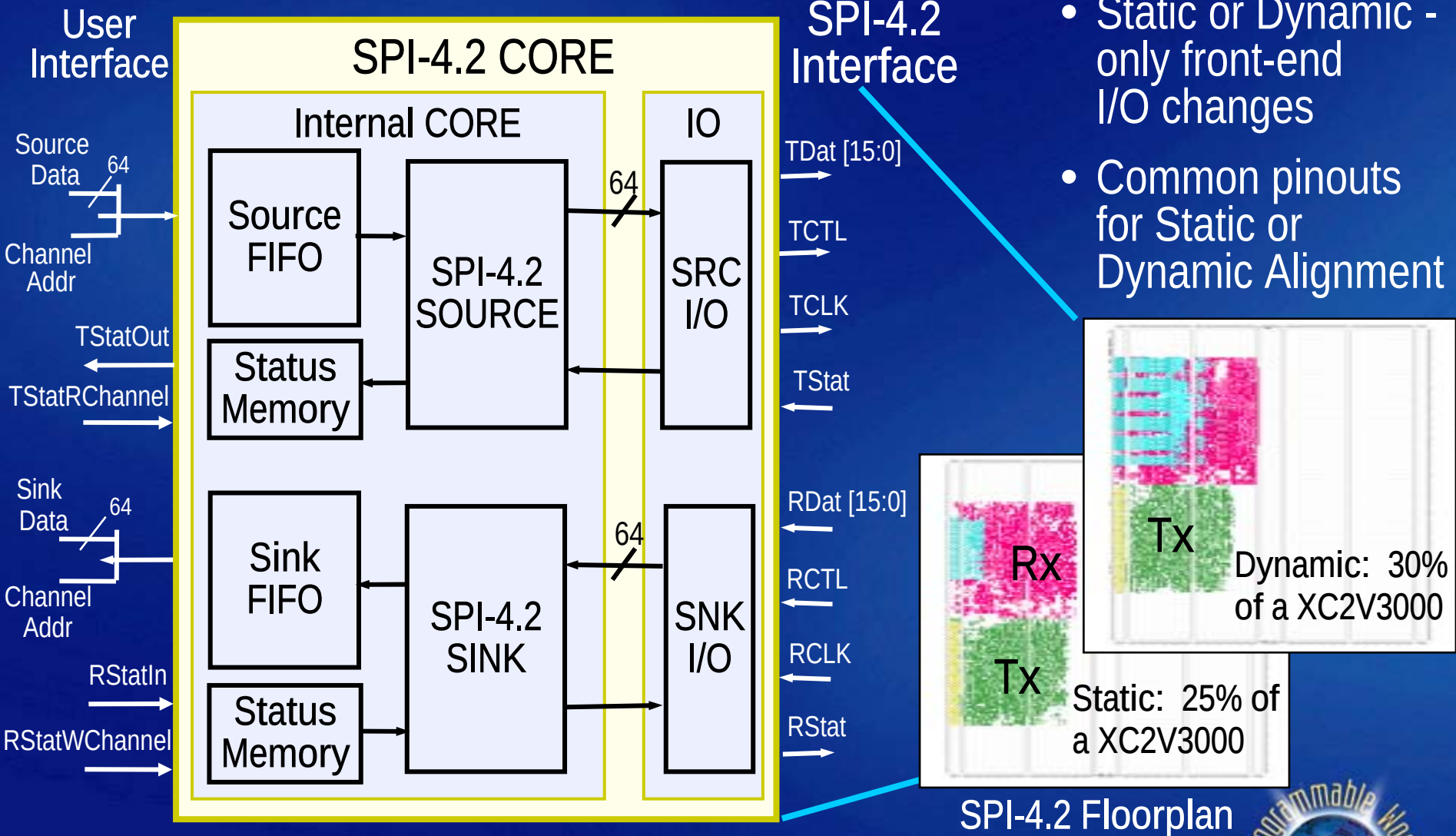


- Framer Aggregation
 - Quad SPI-3 to SPI-4.2
- Backplane Fabric Interface
 - SPI-4.2 to AURORA including NPU example
- Reconfigurable Computing Switch Fabric Network
 - Systran Federal Reconfigurable Computing Platform

Quad SPI-3 to SPI-4.2 Case Study

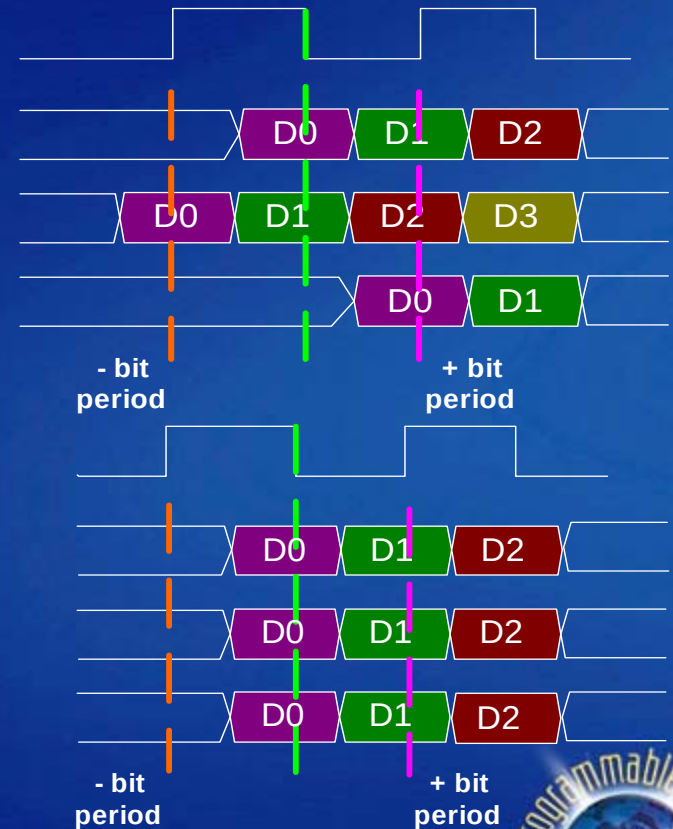
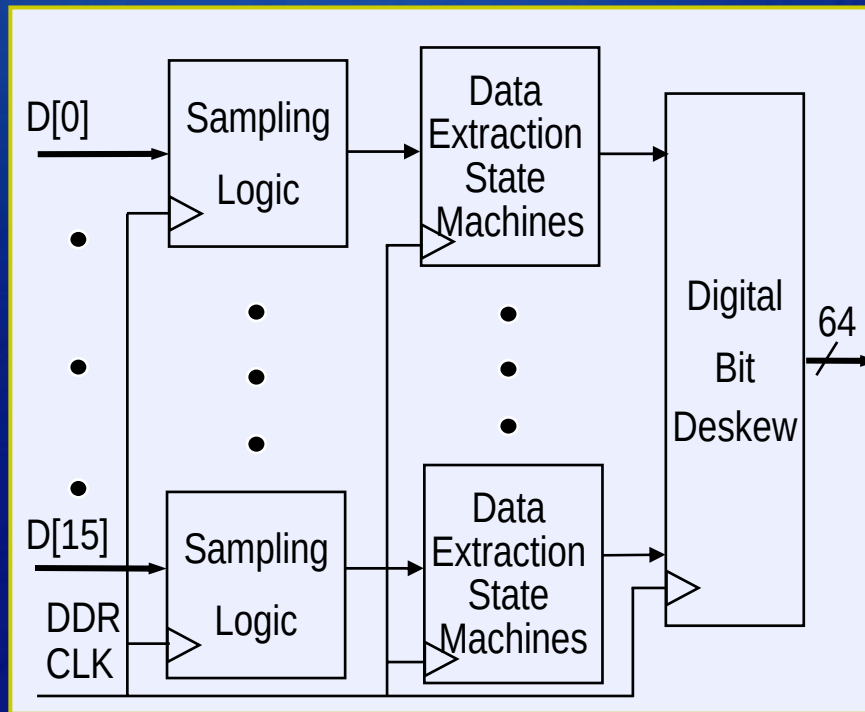


SPI-4.2 Core Implementation



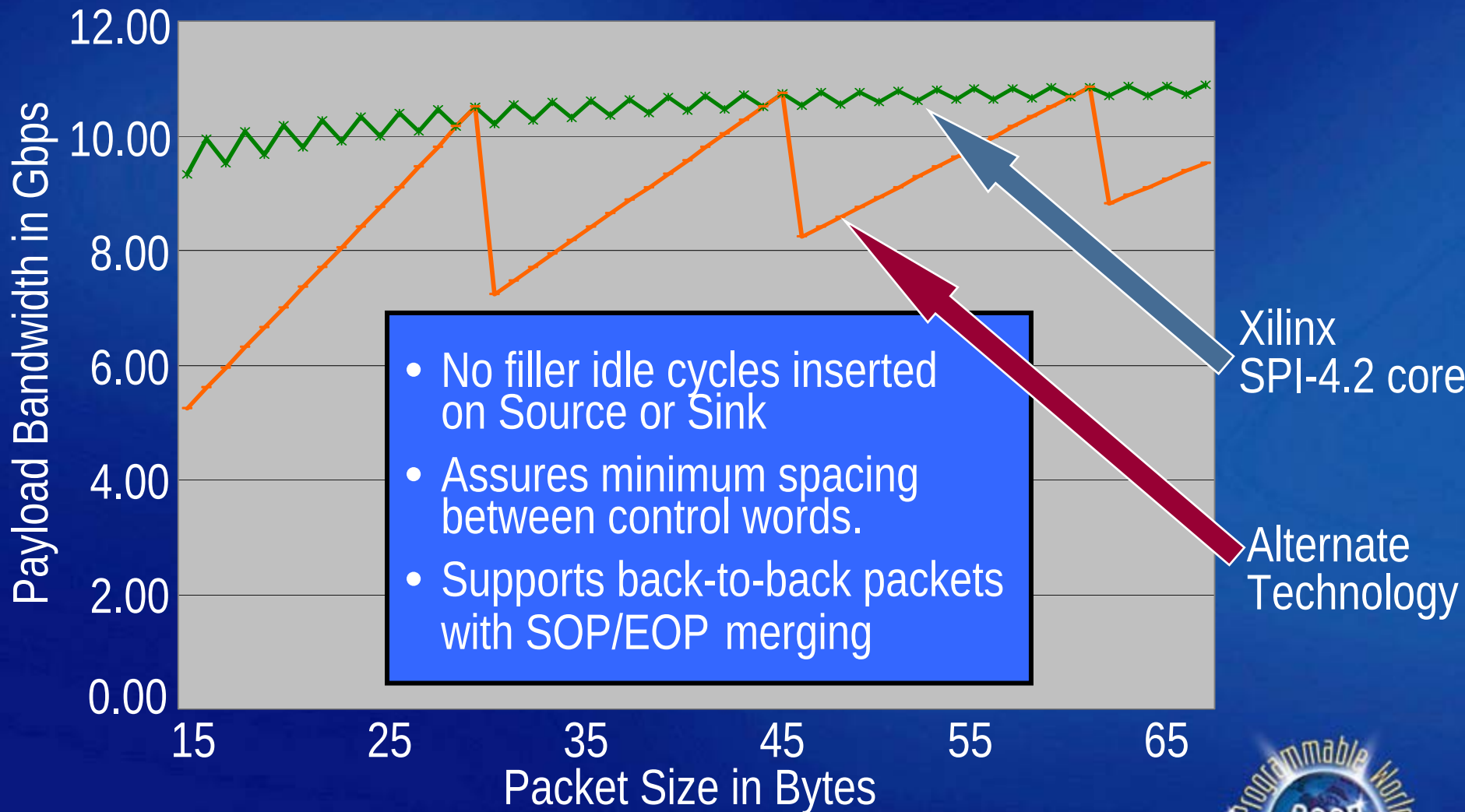
Dynamic Alignment

- Compensate up to +/- one bit period of skew
- State Machines produce 2-bits per rising/falling clock edge
- Digital Bit Deskew uses training patterns to deskew-realign all 16 channels into a 64-bit bus



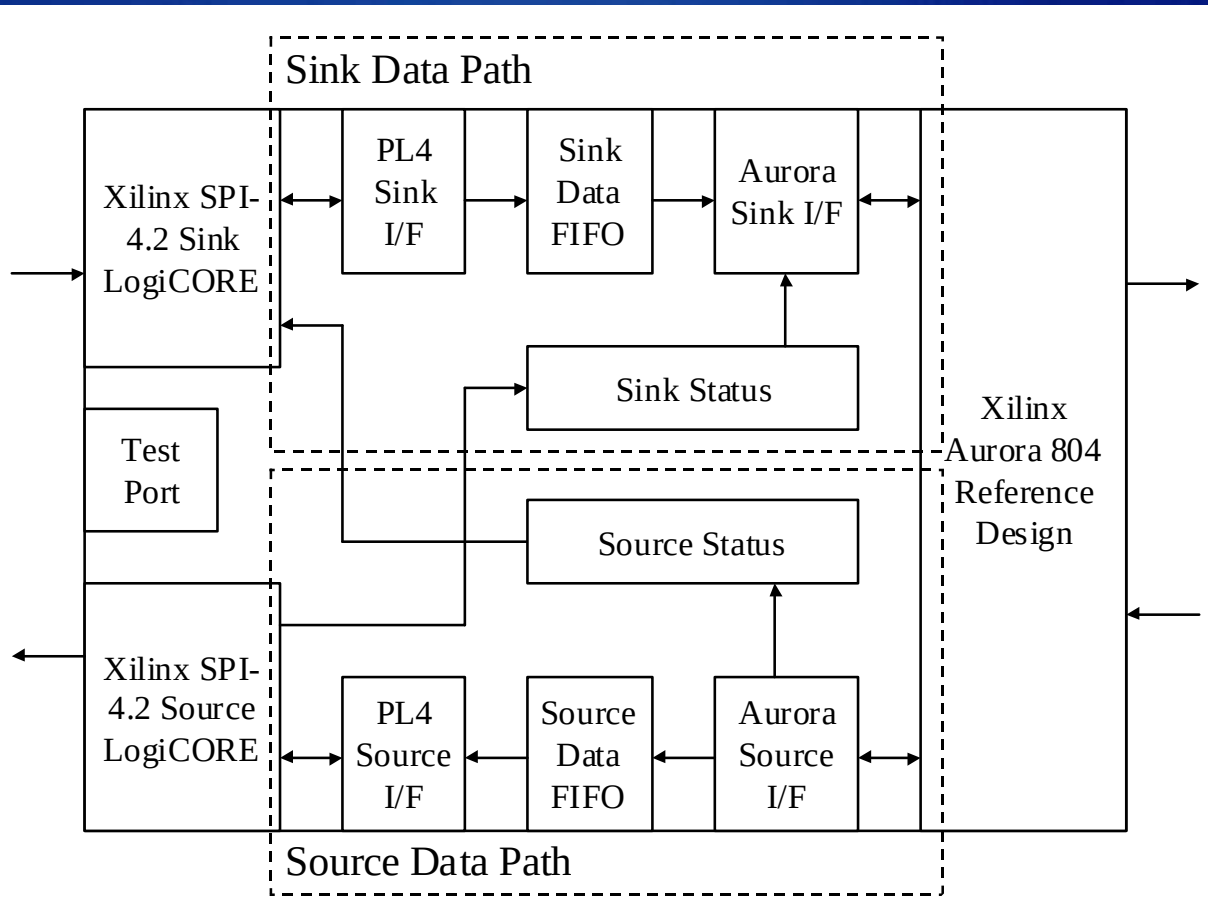
High Bandwidth Solution

SPI-4.2 core optimized for data payload bandwidth



SPI-4.2 to Aurora Case Study

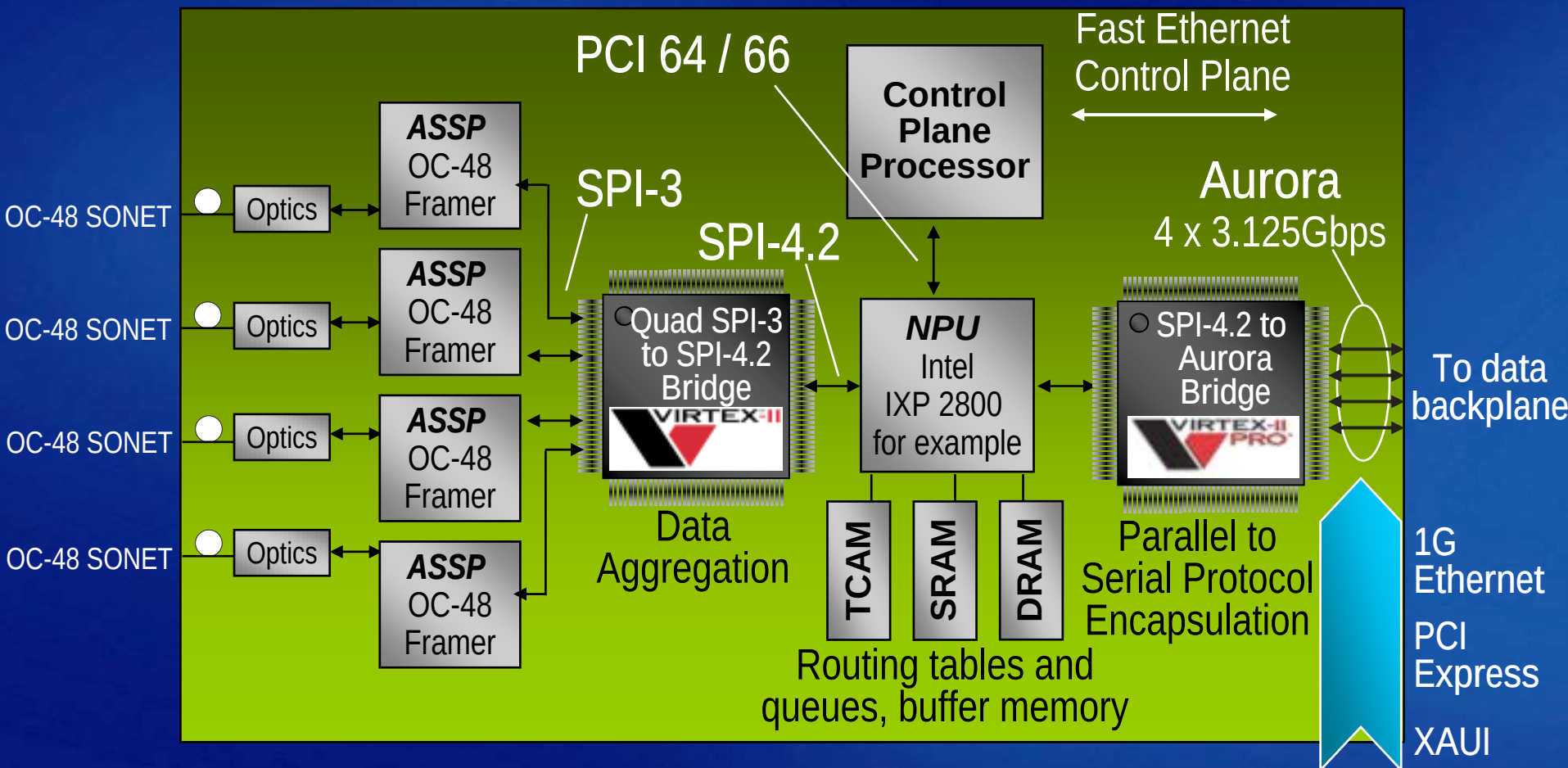
Line Card Bridge For Parallel Interface To Serial Backplane



Aurora

- Xilinx defined link-layer protocol
- Scalable & lightweight
- Provides a transparent interface to encapsulate upper layers of proprietary or industry standard protocols
- Ethernet or TCP/IP
- Preserves software infrastructure investment

NPU Application Example



Virtex-II Pro: Ideal for other PICMG ATCA backplane standards

PCI Express - Complete Endpoint Solution



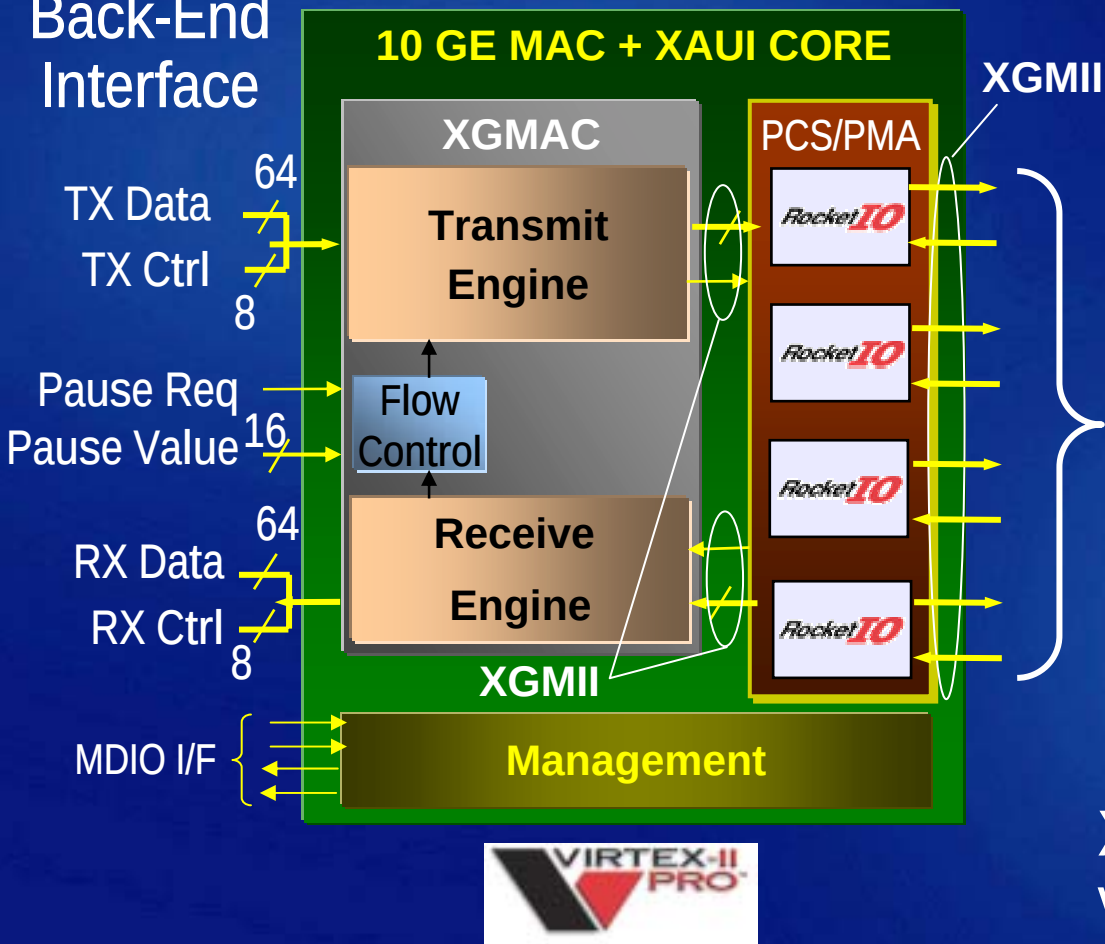
- Provides full physical layer, data link layer, and transport layer
- Compatible with the PCI Express base specification v1.0A
- Local Link universal packetized interface on the back-end
- World's first hardware demo at IDF, Fall 2002

Implementation example
in Virtex-II Pro XC2VP50

- 24% Utilization Single lane
- 2.5G line rate using (1) RocketIOTM transceiver

10 GMAC with XAUI Interface

Back-End Interface



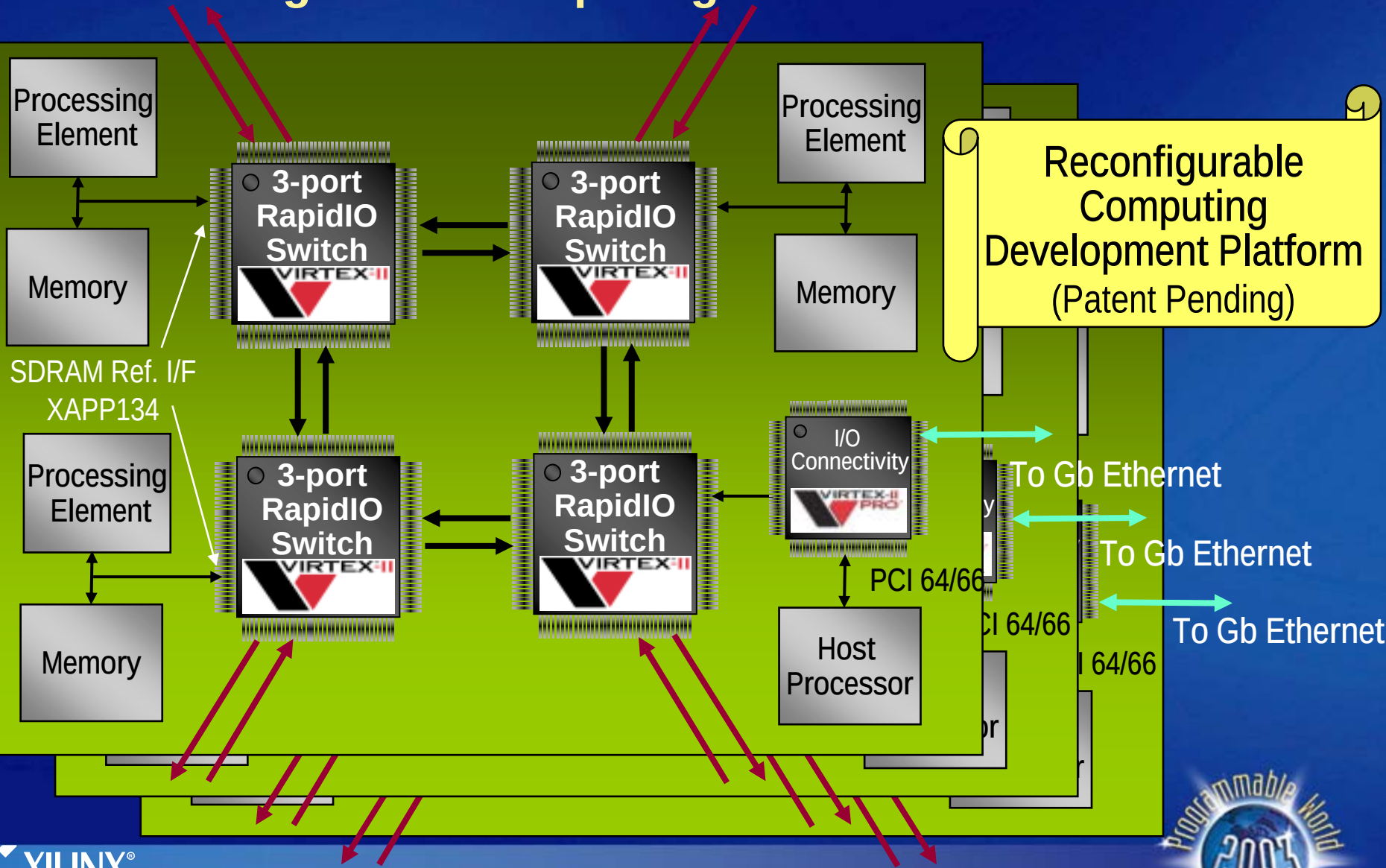
Virtex-II Pro Implementation

- ~ 3800 slices (40% of a 2VP20)
- 3 Global clock buffers
- 4 RocketIO transceivers



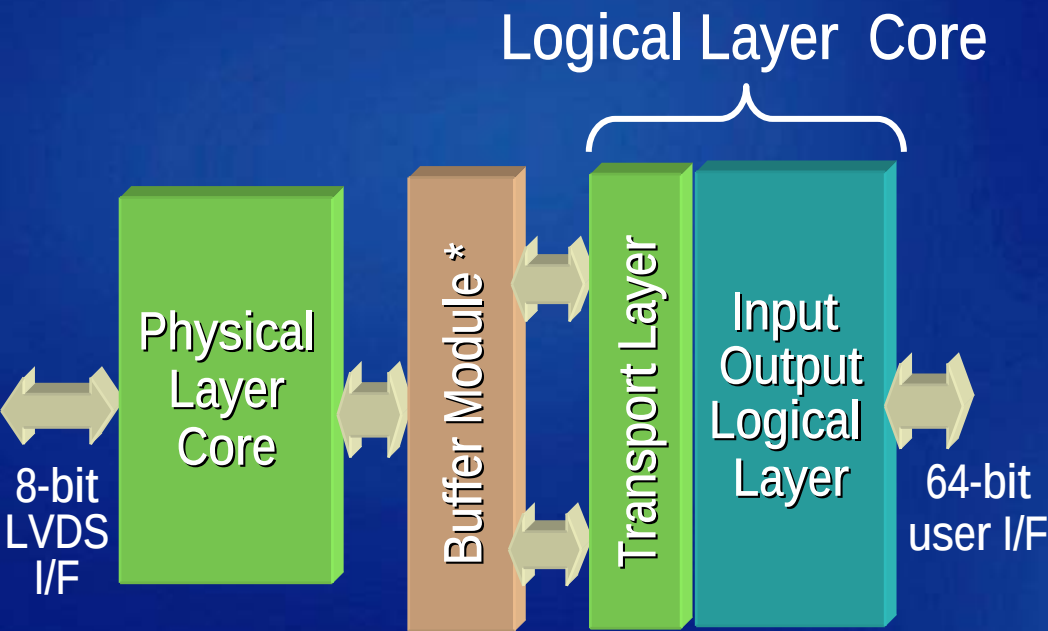
XAUI Floorplan
Virtex-II Pro XC2VP20

RapidIO Case Study: Systran Federal Reconfigurable Computing Switch Fabric Network



RapidIO IP Cores

Physical Layer & Logical Layer



Buffer module available
as a design example

- Complete RapidIO end point solution
- Implements Rev 1.2 of RapidIO Spec
- 8 Gbps aggregate bandwidth
- Physical Layer
 - Uses 19% of a XC2V2000
 - Supports HW error recovery
- Logical Layer
 - Uses 7% of a XC2V2000
- HW demo at CDC '02



Memory Connectivity using Reference Designs

- Tailored to the device technology
- Fully synthesizable VHDL / Verilog
- User-customizable
- Readily transferable to commercial designs
- Full suite of evaluation boards available



SDRAM, SRAM,
FC RAM, RLDRAM

Accelerates development of robust, flexible memory interfaces

Interoperability and Standards Compliance

- Verified interoperability with ASSP suppliers
 - Increases customer confidence
 - Drives customer-ready reference designs
 - Simplifies PCB implementation
 - Improved time-to-market

The screenshot shows the Xilinx website's 'Products' section, specifically the 'Proven Interoperability Solutions' page. It features a navigation bar with links like HOME, PRODUCTS, END MARKETS, SUPPORT, EDUCATION, ONLINE STORE, and CONTACT. Below the navigation bar, there's a section titled 'Proven Interoperability Solutions' with a paragraph explaining the importance of interoperability and a link to the 'Reference Design Alliance Program'. A table follows, listing various ASSP solutions and their compatibility with Xilinx devices.

ASSP Vendor	ASSP Device	ASSP Device Type	Video 8 Carrier?	Industry Standard	Std. Format Available?
AMEC	Reticon Processors with VIC-40 interface	Reticon Processor Families	✓	16:4:4 to EPIC	Yes
Chips & Media	ASSP T31815	ISP		Compliance for T31815 derivatives	Yes
Sec. Microsystems	80486	Reticon Processor	✓	Full Accountant	Yes
Emulex	BCM4040	Multi-core Data Switch	✓	10GbE	No
Cypress Semiconductor	CY8C1092, CY8C1092B & MPU	CMU		100% compliance for	Coming
Intel	255400 EPF	Optical Transceiver	✓	2400 Gbps Channel	Yes
Intel	Teracore FPD	FPD	✓	4Kx4K	Yes

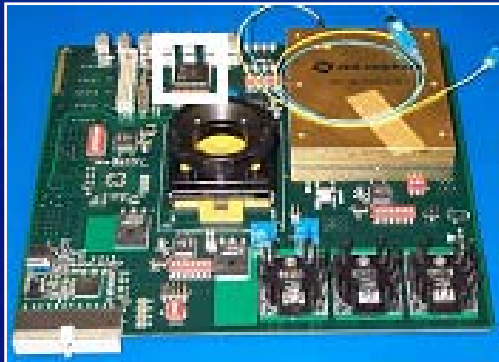
Proven Interoperability



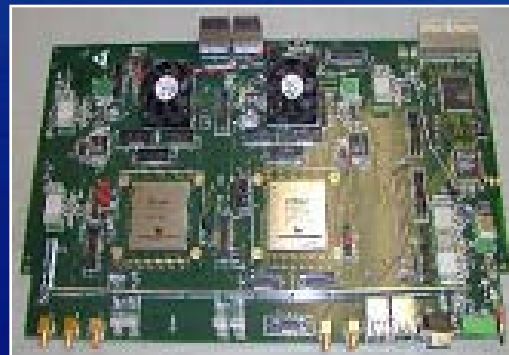
Vitesse Meigs-II
10Gbps Ethernet MAC



AMCC Ganges-II
PHY device



Mindspeed M29730
PHY device



PMC S/UNI 9953
PHY device

- Validates...
 - Electrical signaling
 - Protocol compliance
 - Performance
- Proven in hardware
- Extensive ecosystem

OIF Physical and Link Layer Interoperability Demonstration

- Successful **public** interop test
 - Vitesse Meigs-II™ VSC7321 MAC
 - NEC Ridge Tx/Rx/PHY chipset
- Used LVDS demo board
 - Virtex-II XC2V1000 + SPI-4.2 core
 - Dynamic Phase Alignment
 - 700 Mbps
- Only FPGA supplier to participate



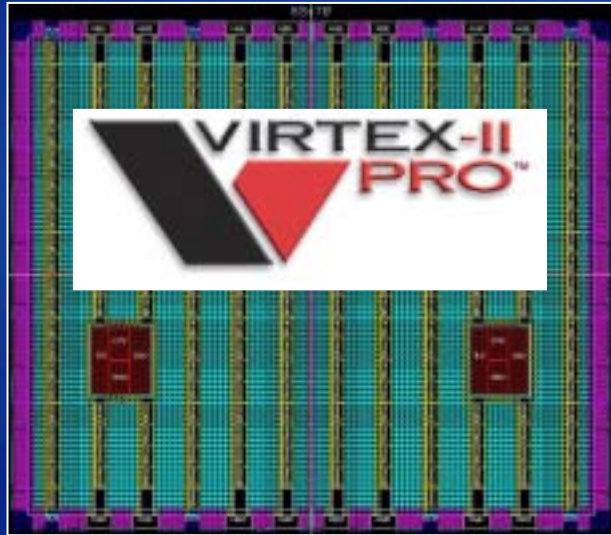
http://www.oiforum.com/public/pressroom/OIF_OFC03.pdf

Ethernet Interoperability

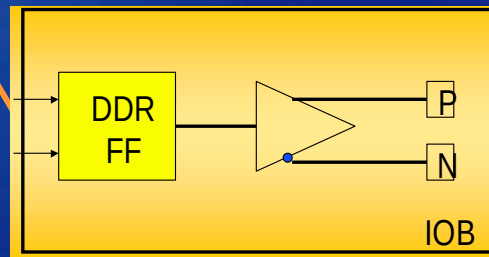
- Xilinx Ethernet solutions tested by UNH Interoperability Lab
 - 10/100, 1GE, and 10GE MAC
 - Tested against IEEE compliance standards
 - Multiple configurations tested, including XAUI
- UNH using Xilinx board for pre-test and pattern generation
- Only FPGA supplier participating



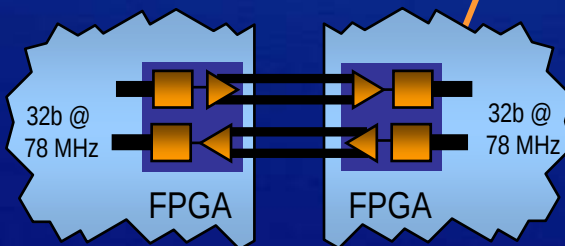
Serial and Parallel Connectivity on One Platform



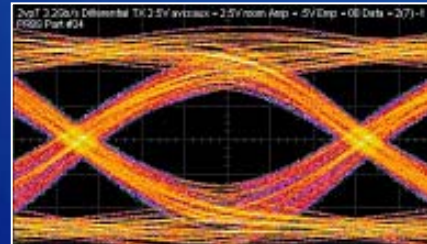
SelectIO™-Ultra for parallel interfaces



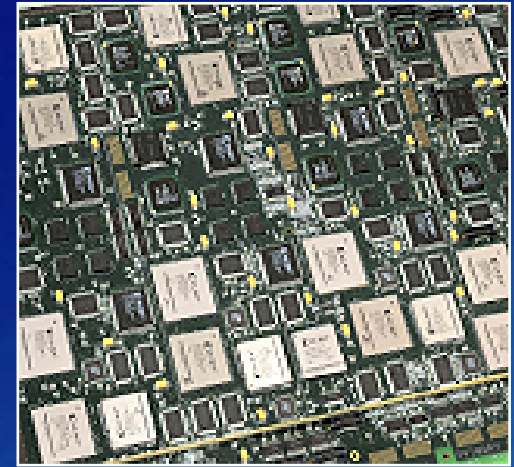
- 25 I/O Standards
- XCITE Technology
- Dedicated DDR Registers
- 840 Mbps LVDS
- 644 Mbps SDR



Multi-Gigabit Serial Transceivers
Up to (24) 3.125 Gbps transceivers



Ultimate Connectivity



LAN / WAN / MAN

- 10/100 Ethernet (MII)
- 1Gb Ethernet (GMII)
- 10Gb Ethernet (XGMII)
- 1Gb Ethernet (Phy)
- 10Gb Ethernet (XAUI)
- OC48
- OC192
- OC768

Boards / Backplanes

- PCI 32/33
- PCI 64/66
- PCI-X 133
- RapidIO
- Ser.
- Fibre chan.
- 10GE(XAUI)
- SONET
- RapidIO
- CSIX
- HyperTransport
- InfiniBand
- PCI Express
- Aurora

Chip-to-Chip

- PCI 32/33
- PCI 64/66
- PCI-X 66, 133
- RapidIO
- SFI-4
- 10GE (XAUI)
- SPI-3 / SPI-4.2
- Flexbus 4
- CSIX
- HyperTransport
- XSBI
- PCI Express



- Parallel Standards – enabled by SelectIO™-Ultra technology
- Serial Standards – enabled by RocketIO™ technology

Solving the Connectivity Challenge

Platform FPGAs + IP Cores + Proven Interoperability

Design to new
emerging standards

Update as the
standard evolves

Reduce risk and
minimize “re-spins”

Deliver more robust and
competitive end products



xilinx.com/connectivity

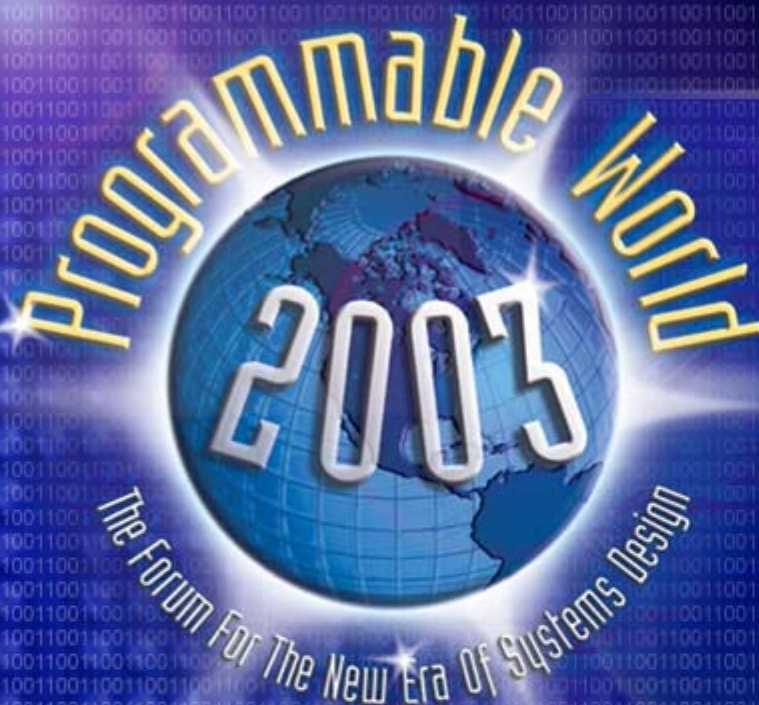
References

- **Helpful Links**

- Connectivity Central: <http://www.xilinx.com/connectivity>
- Aurora: <http://www.xilinx.com/aurora>
- Proven Interoperability:
http://www.xilinx.com/company/reference_design/interop_solutions.htm
- Signal Integrity Central: <http://www.xilinx.com/signalintegrity>
- Metro Access Networks: <http://www.xilinx.com/esp/optical>

- **Design Resources - Available on PW03 Resource CD**

- Datasheets: SPI-4.2, Ethernet MAC, 10G Ethernet MAC, RIO
- Memory Interface Reference Designs / Resources:
RLDRAM, FCRAM, DDR SDRAM, QDR SRAM



Thank You!